



MSP-LEGO: Modular Series-Parallel (MSP) Architecture and LEGO Building Blocks for Non-isolated High Voltage Conversion Ratio Hybrid Dc-Dc Converters

Yueshi Guan^{1,2}, Ping Wang¹, Ming Liu¹, Dianguo Xu², Minjie Chen¹

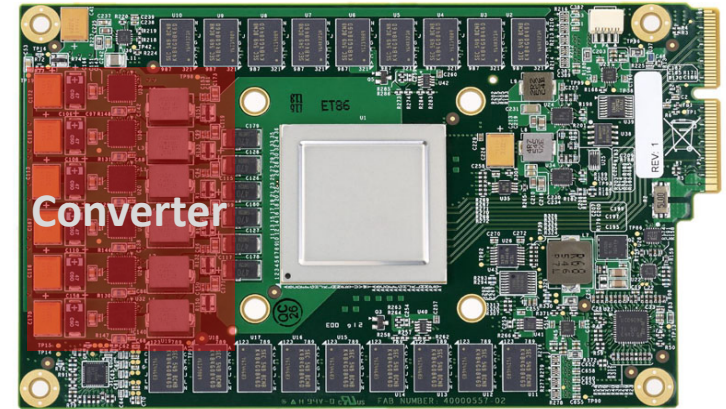
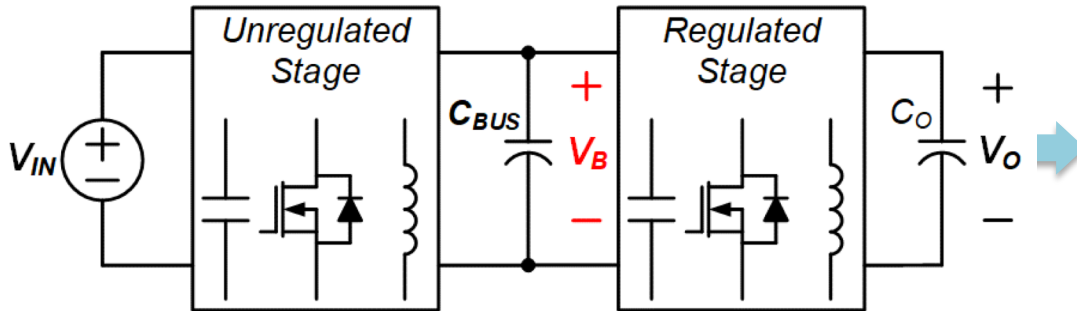
¹Princeton University, USA

²Harbin Institute of Technology, China



High Voltage Conversion Ratio

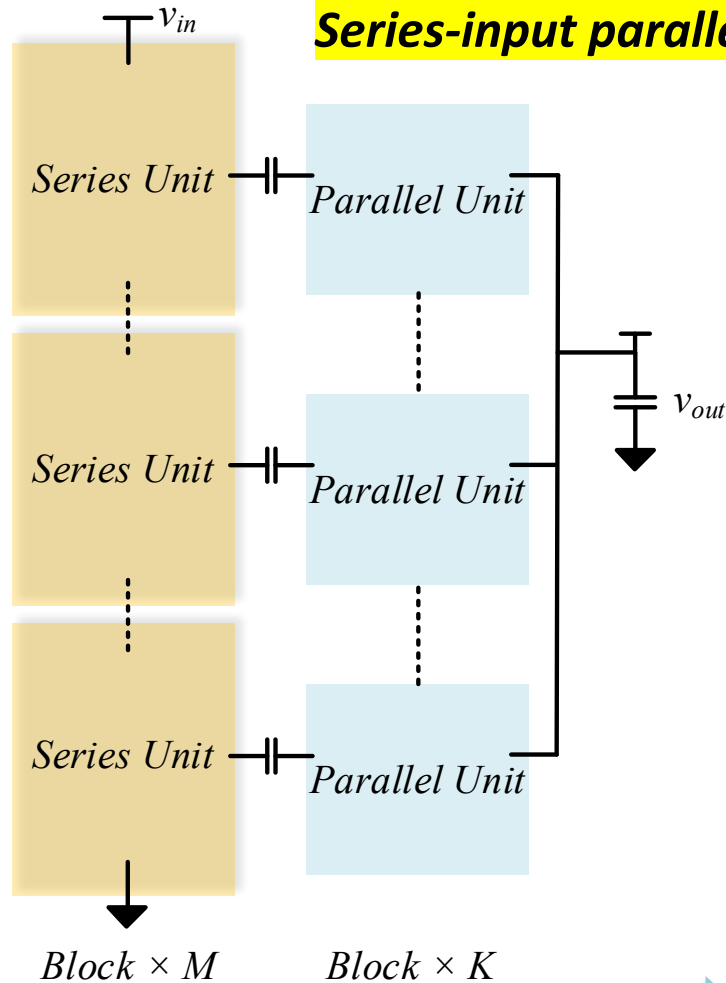
High voltage conversion ratio topologies



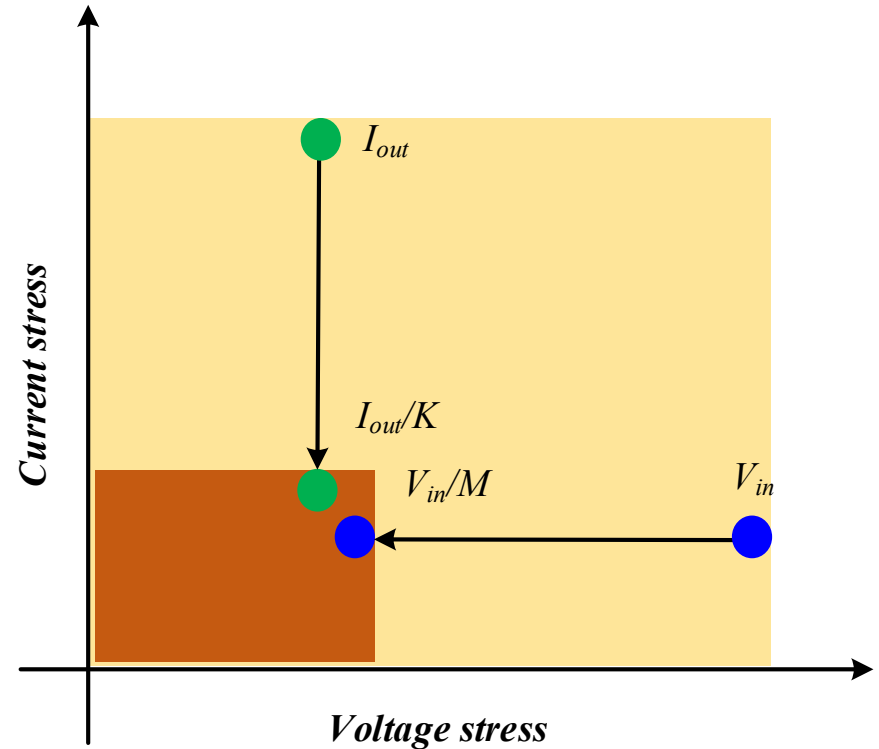
- **Two-stage transformer-based solutions**
 - Low light load efficiency & low power density
 - Narrow operation range
- **Single-stage hybrid-switched-capacitor-based solutions**
 - Transformer-free & high modularity & non-isolated
 - High light load efficiency & high power-density
 - High operating bandwidth

Modular Series-Parallel Architecture

Series-input parallel-output configuration



MSP architecture

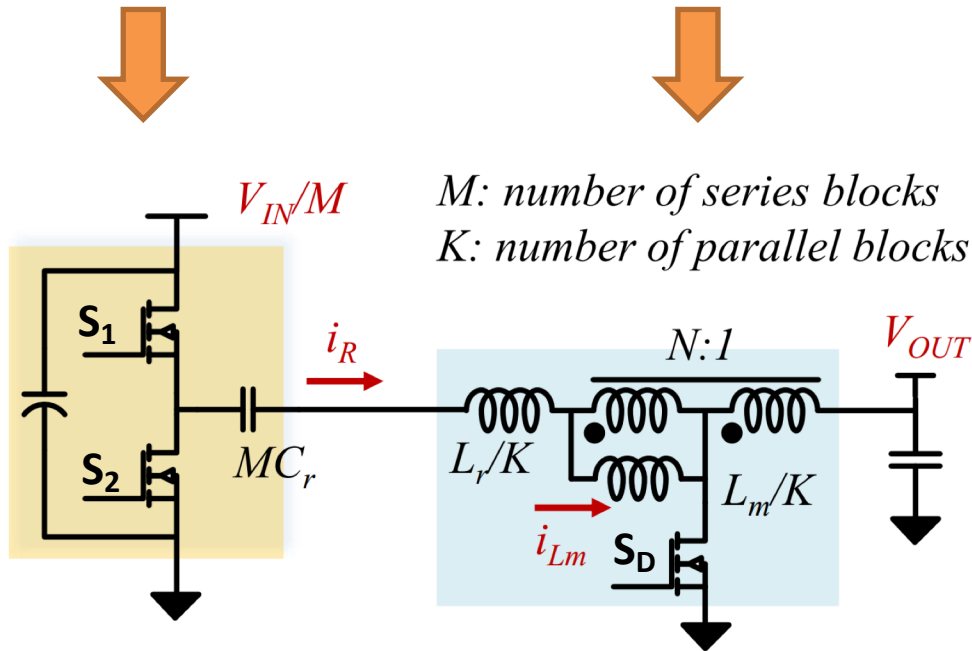


- Merged operation of the two units
- Reduced switch voltage stress
- Reduced switch current stress
- Reduced overall $V \cdot I$ ratings

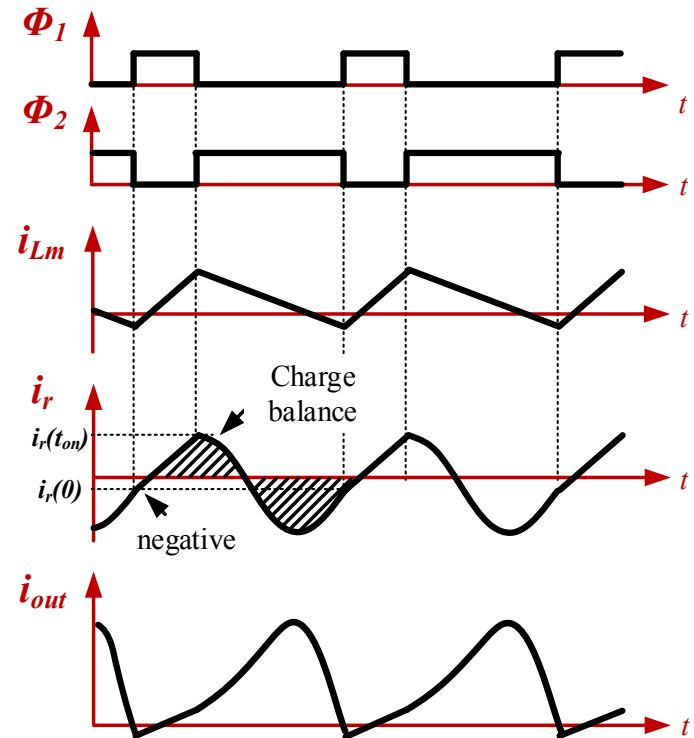
A SC-TaB Example Topology

Series Unit
a half bridge

Parallel Unit
a coupled inductor



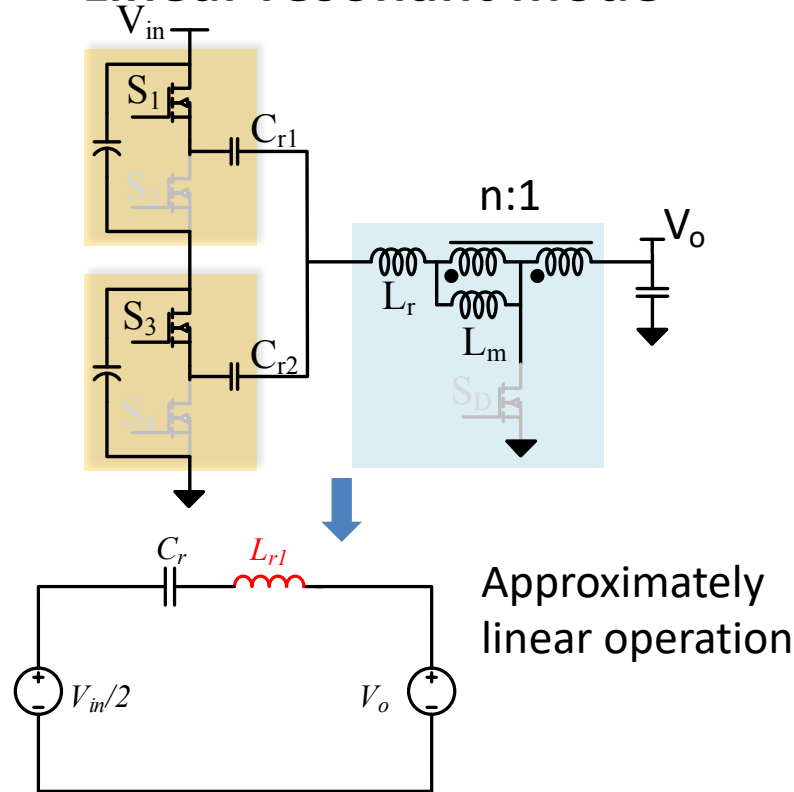
A Series-capacitor tapped buck (SC-TaB) converter



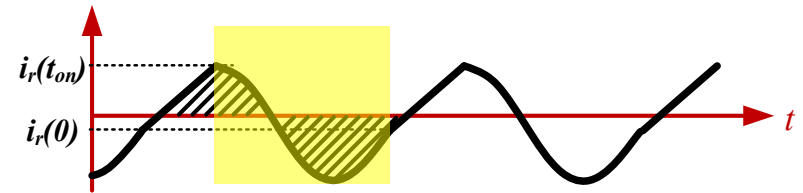
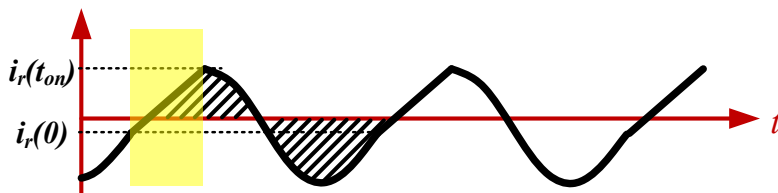
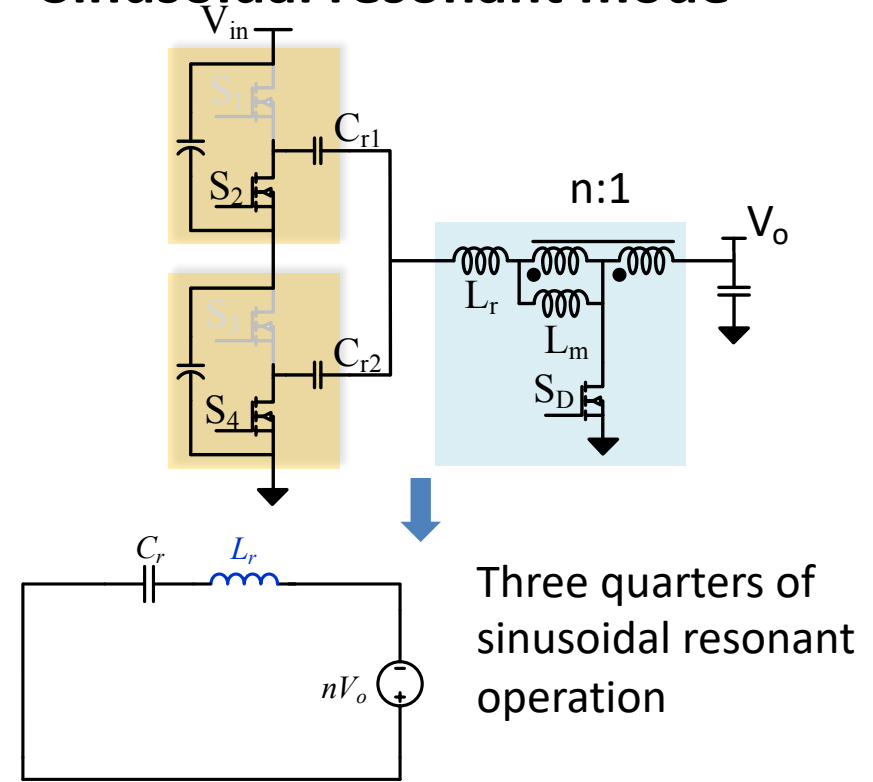
Interleaved operation to reduce the output current ripple

Semi-Resonant Operation

Linear resonant mode




Sinusoidal resonant mode



Extended Voltage Gain

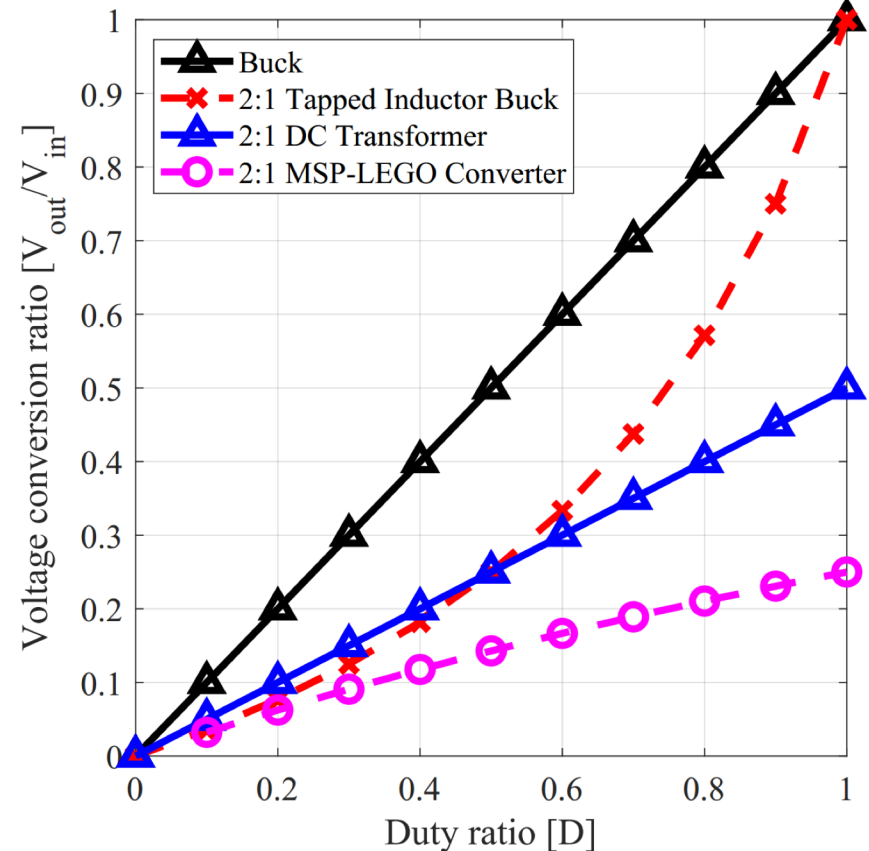
$$\frac{V_o}{V_{in}} = \frac{1}{1+n} \frac{\sin(\omega_r T_s (1-D)) + \frac{N}{M} (\cos(\omega_r T_s (1-D)) - 1)}{\sin(\omega_r T_s (1-D)) + \frac{N}{M} (\cos(\omega_r T_s (1-D)) - 1) - \omega_r T_s (1-D)}$$



 Simplification
 (linear operation)

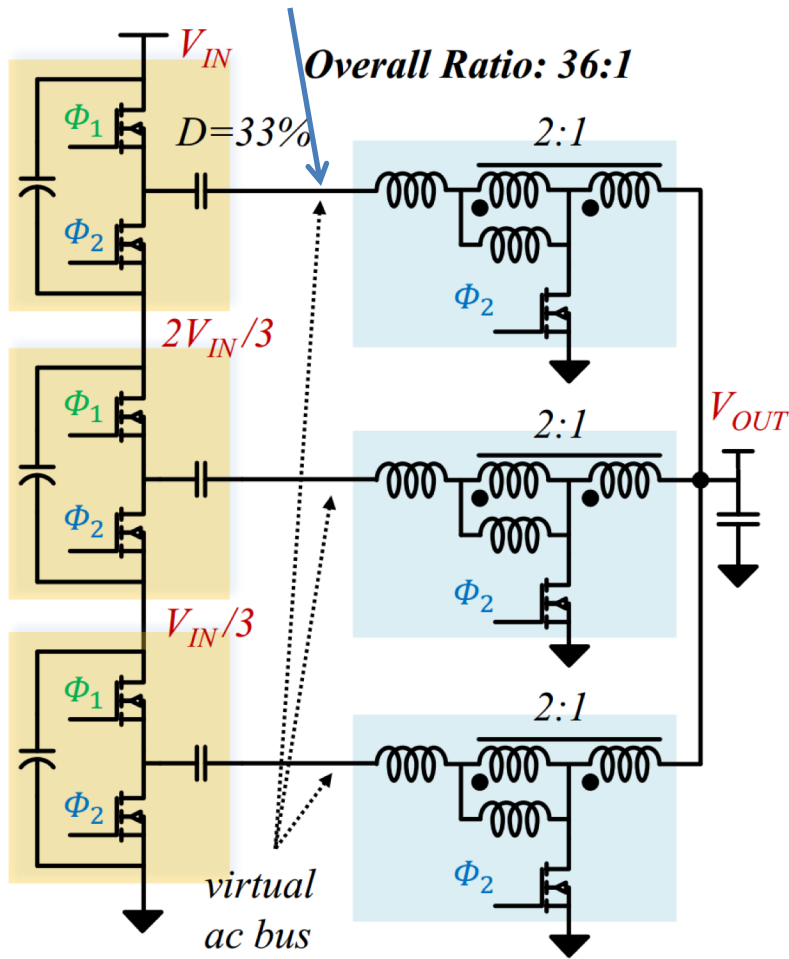
$$\frac{V_{out}}{V_{in}} = \frac{1}{M} \frac{(N+1)DL_m}{(N+1)^2 L_m - N^2 L_r}$$

- Soft-switching operation
- High voltage conversion ratio
- Extend the voltage conversion ratio by 3x compared with Buck



MSP-LEGO Converter (split ac bus)

Split virtual ac bus



Operation Principles

- Linear Extendable Group Operated
- Switched capacitor building block
- Switched inductor building block
- Automatic current sharing
- Low component count

Conversion Ratio Breakdown

- 3:1 from the series input stack
- 3:1 from the duty ratio
- 4:1 from the semi-resonant operation
- $3 \times 3 \times 4 = 36:1$

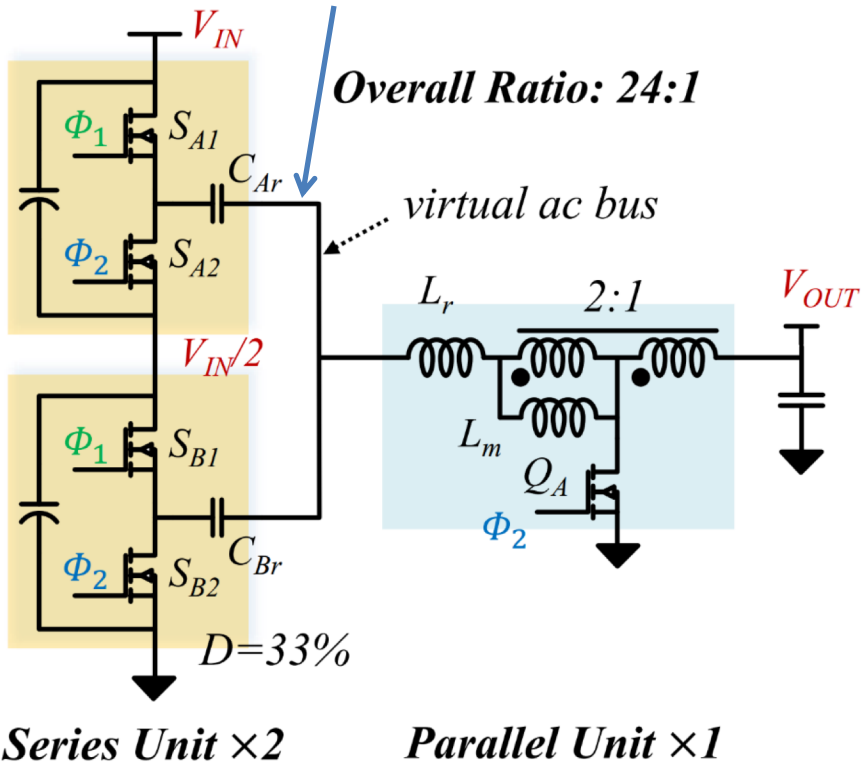
Series Unit $\times 3$

Parallel Unit $\times 3$

MSP-LEGO converter (merged ac bus)



Merged virtual ac bus



Key principles:

- C_{Ar} and C_{Br} effectively connected in parallel
- Automatic voltage balancing of series units

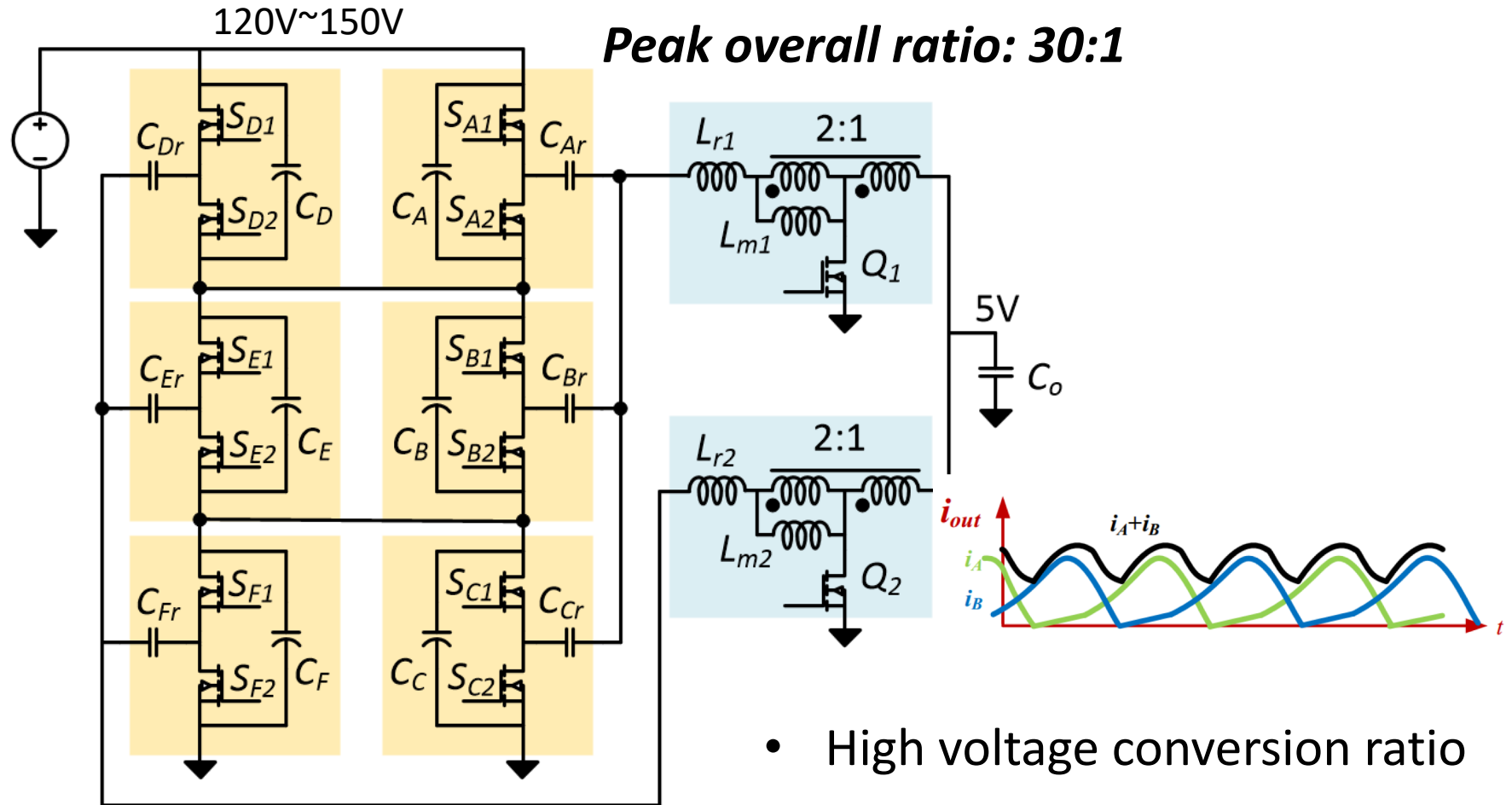
Advantages:

- Flexible series-parallel combinations

Disadvantages:

- Current sharing not guaranteed

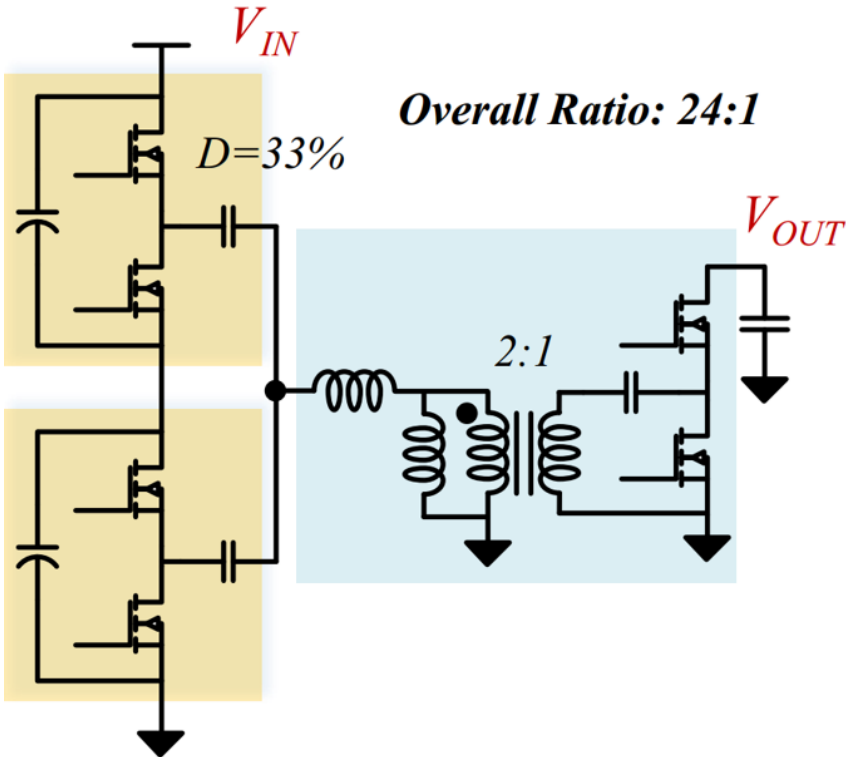
Interleaved MSP-LEGO converter



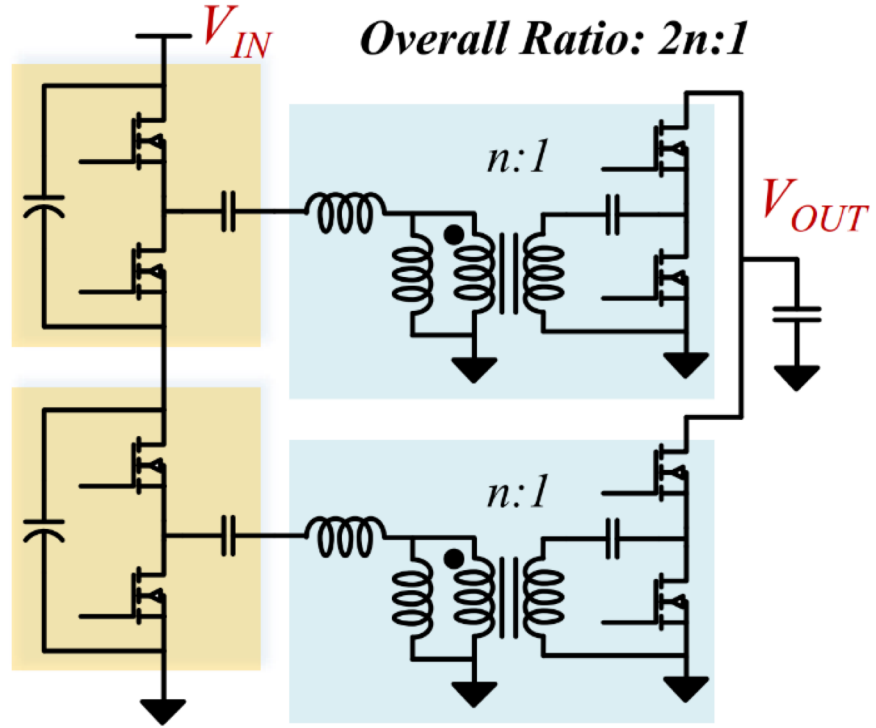
MSP-LEGO converter with two interleaved modules

- High voltage conversion ratio
- Reduced output current ripple
- Reduced input capacitor size

Other Isolated MSP-LEGO Options

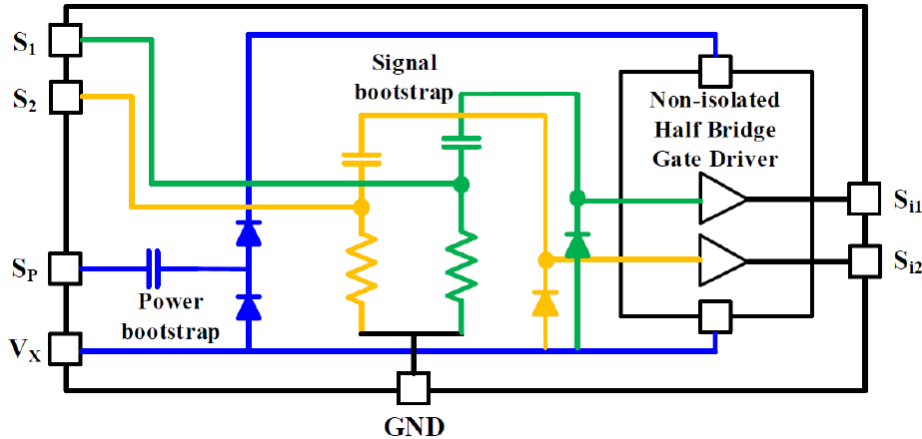


**Isolated half-bridge
(merged ac bus)**



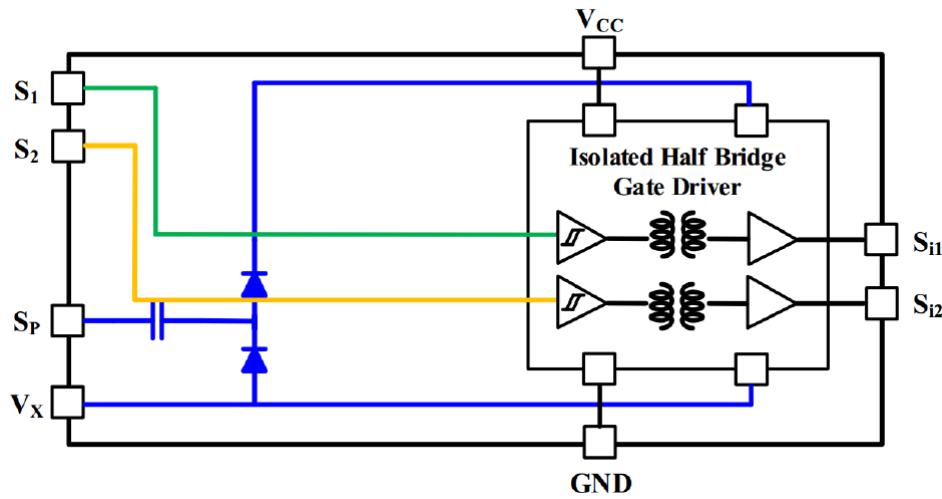
**Isolated half-bridge
(split ac bus)**

Modular Gate Drive Circuits



Boot-strap gate driver

- Signal bootstrap
- Power bootstrap
- Adopted in prototype

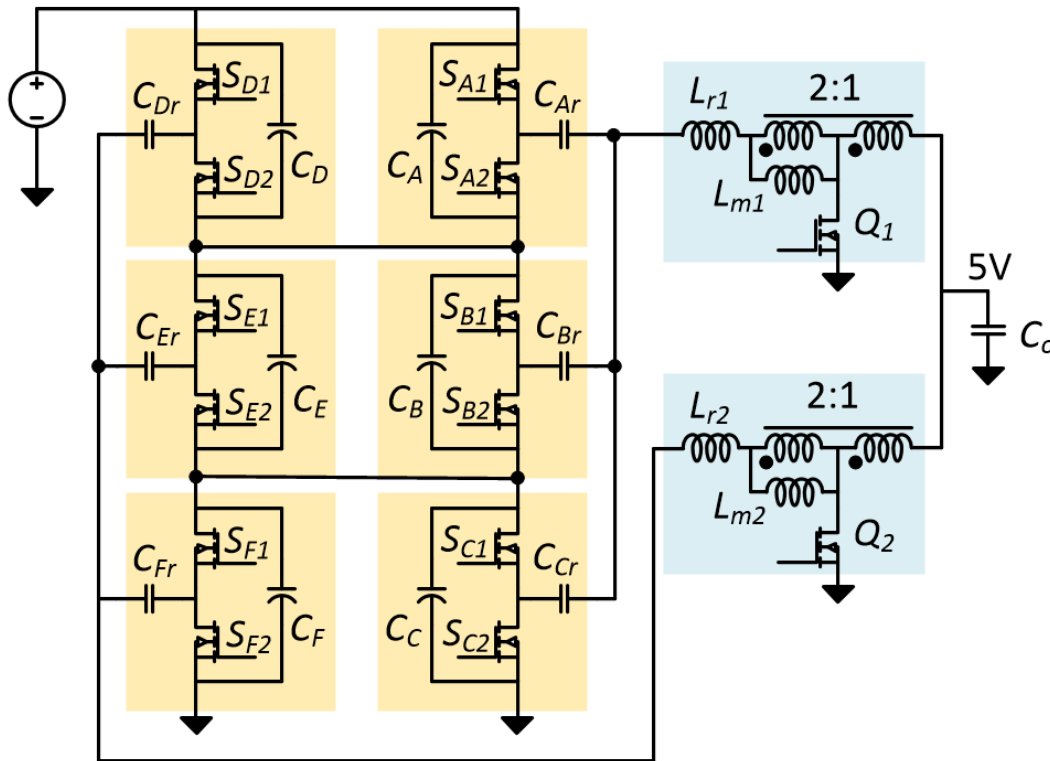


Capacitive isolated gate driver

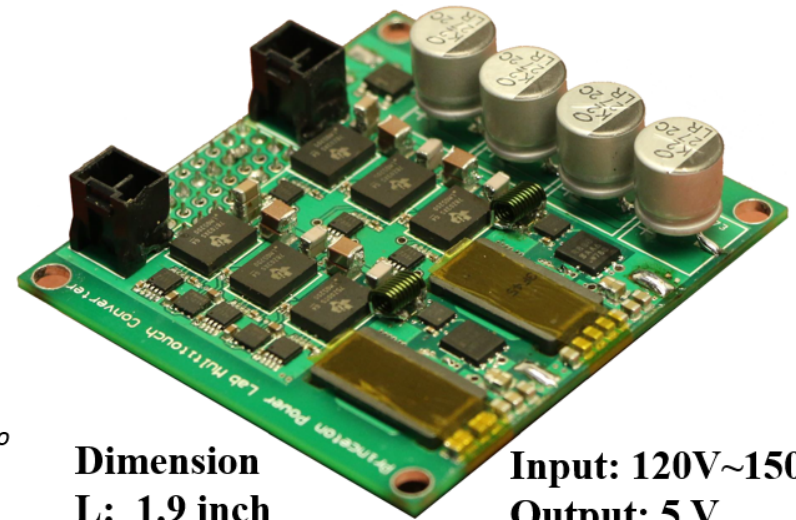
- Power bootstrap
- IL711 isolated coupler

A 110W/in³ MSP-LEGO prototype

Peak overall ratio: 30:1

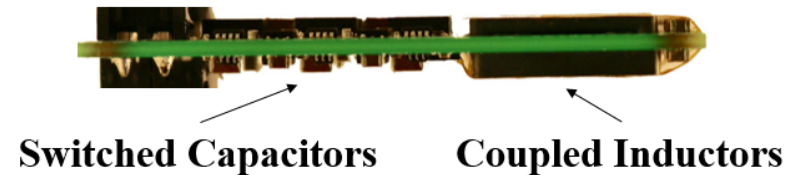


Six input units and two output units



Dimension
L: 1.9 inch
W: 1.6 inch
H: 0.3 inch

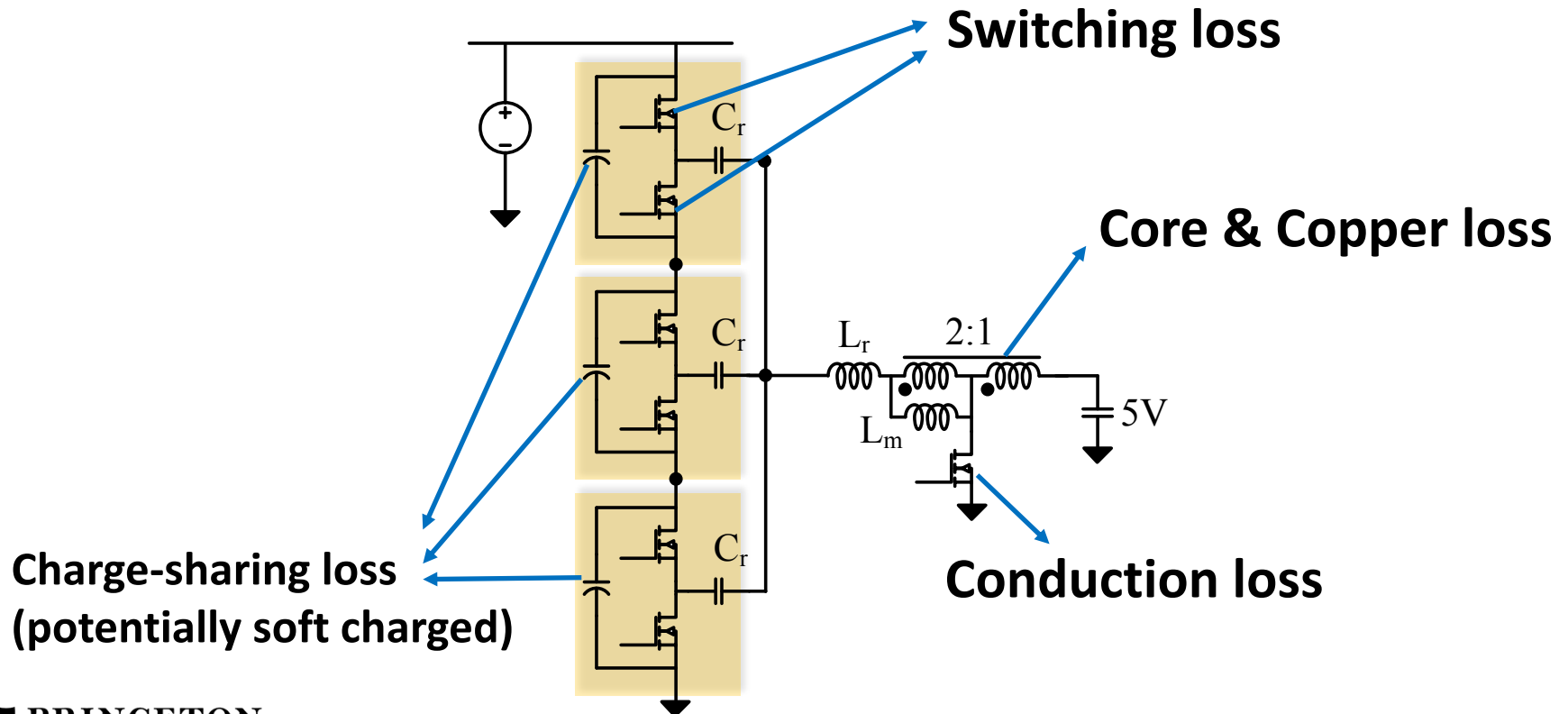
Input: 120V~150 V
Output: 5 V
Power: 100 W
Efficiency: 91.5%



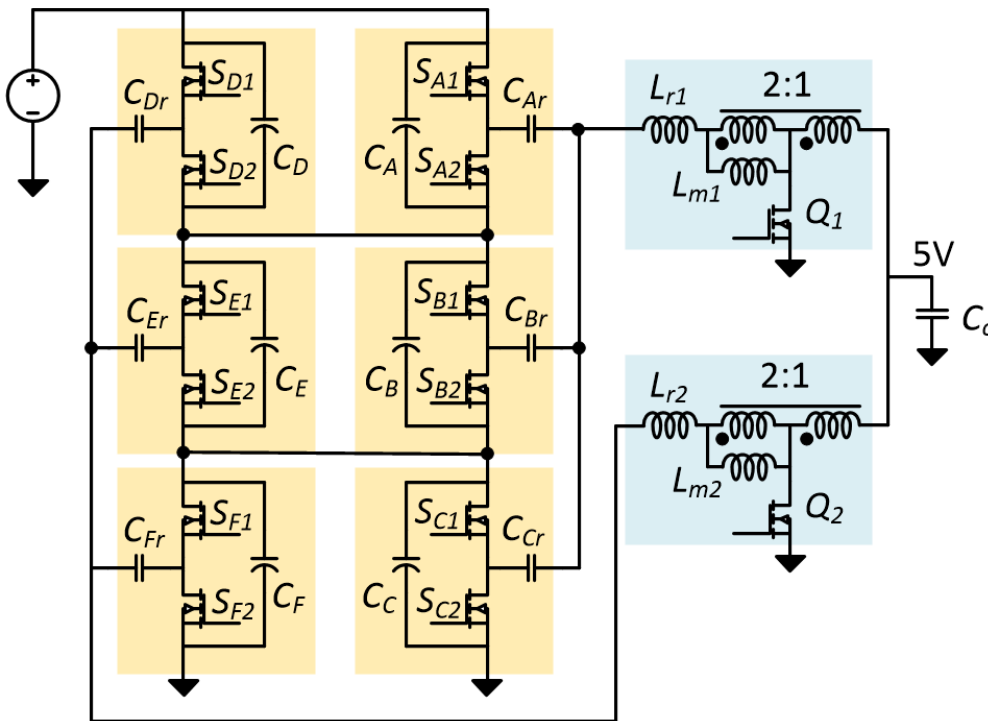
- Power density: 110 W/in³
- Switching frequency: 600kHz
- All gate-drive & boot-strap circuit included

Converter Parameter Design

- Design capacitors to balance the charge sharing loss and size
- Design coupled inductor to achieve ZVS and minimize core loss
- Select switches to minimize the switching and conduction losses
- Select the optimal operating frequency (600kHz)



Prototype Specifications

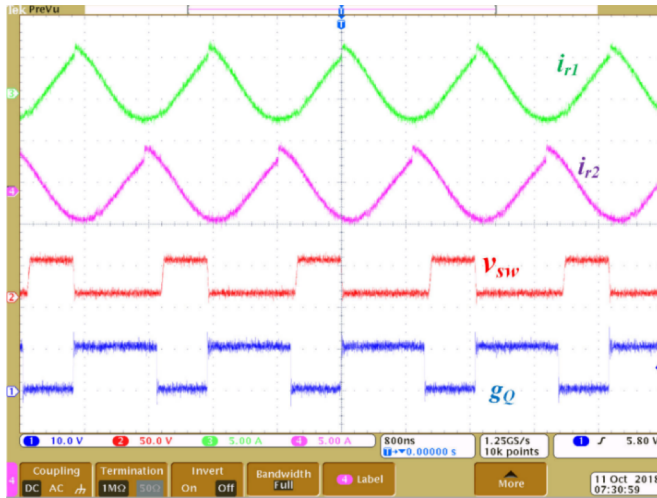


BOM of the prototype converter

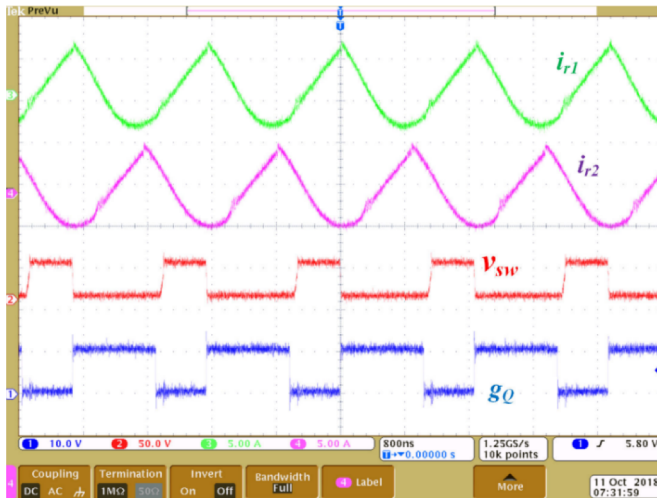
Device Symbol	Component Description	
C_{Ar}, C_{Dr}	C0G Ceramic,	200V,
	100 nF+39 nF+2x22 nF	
C_{Br}, C_{Er}	C0G Ceramic,	100V,
	100 nF+39 nF+2x22 nF	
C_{Cr}, C_{Fr}	C0G Ceramic,	50V,
	100 nF+39 nF+2x22 nF	
L_{r1}, L_{r2}	173 nH	
L_{m1}, L_{m2}	1.1 μ H	
S_{A1}, S_{A2}	TI LMG5200 integrated GaN half-bridge modules	
S_{F1}, S_{F2}		
Q_1, Q_2	2x Vishay SIR890DP silicon MOSFETs	
$C_A - C_F$	2x X5R Ceramic, 50V, 10 μ F	
C_o	36x X5R Ceramic, 6.3V, 22 μ F	
Inductor	Ferroxcube ER18, Core material 3F45, turns ratio 2:1, 4-layer PCB	

- The half-bridge module is implemented with TI GaN LMG5200
- The coupled inductor is implemented as a PCB planar inductor

Experimental Results

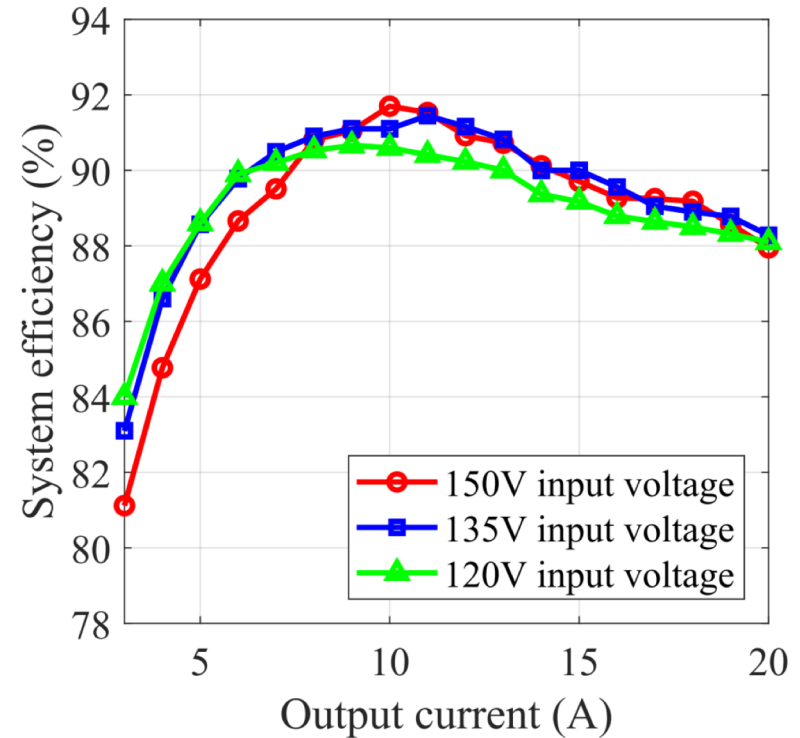


3A output current



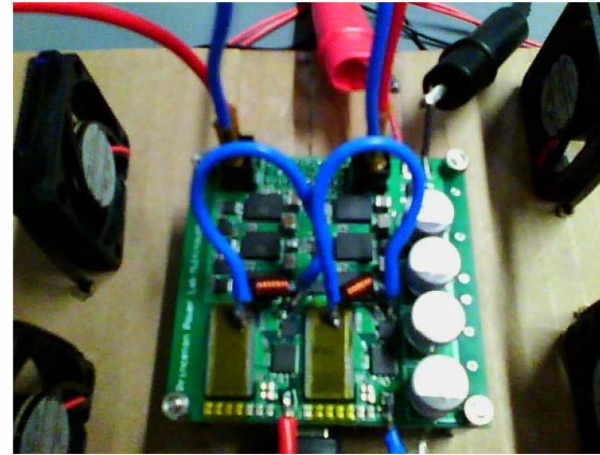
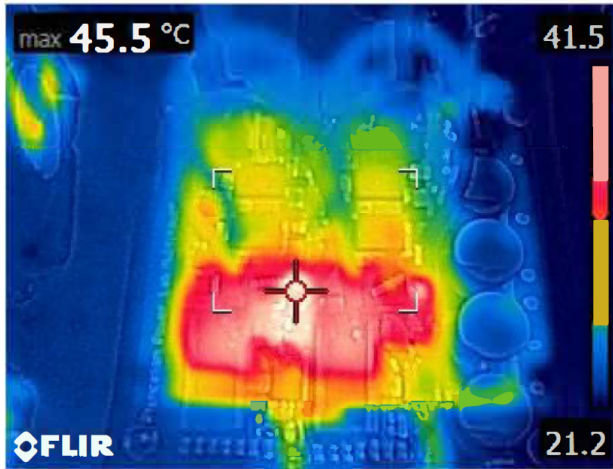
10A output current

Input: 120V-150V, Output: 5V, Current, 20A

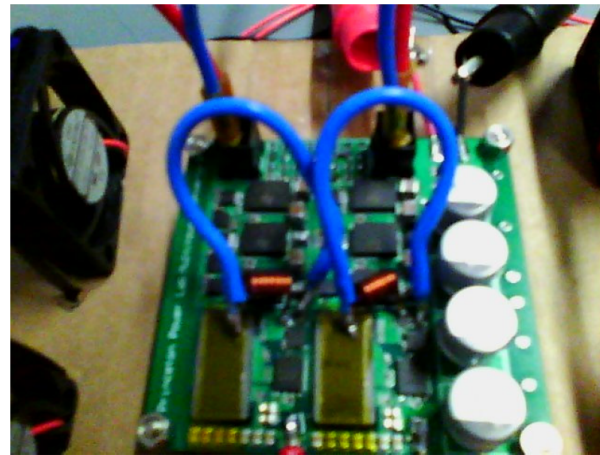
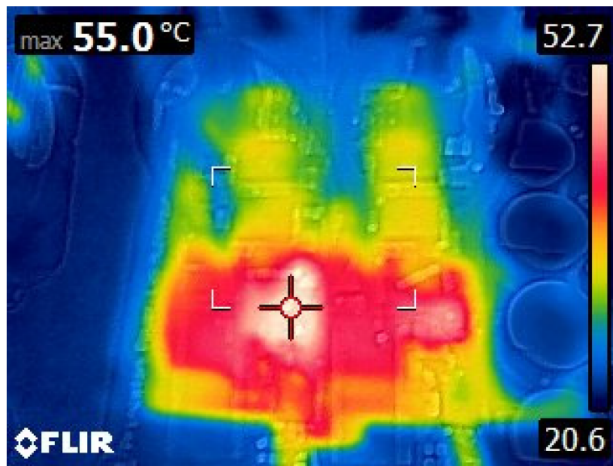


- Peak efficiency 91.5% with 10 A output current
- Over 88% efficiency across a wide voltage/power range

Converter Thermal Images



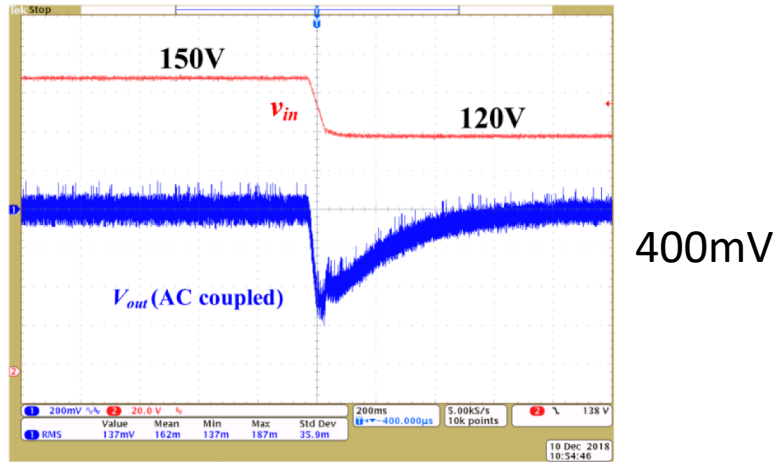
3A output current (200LFM)



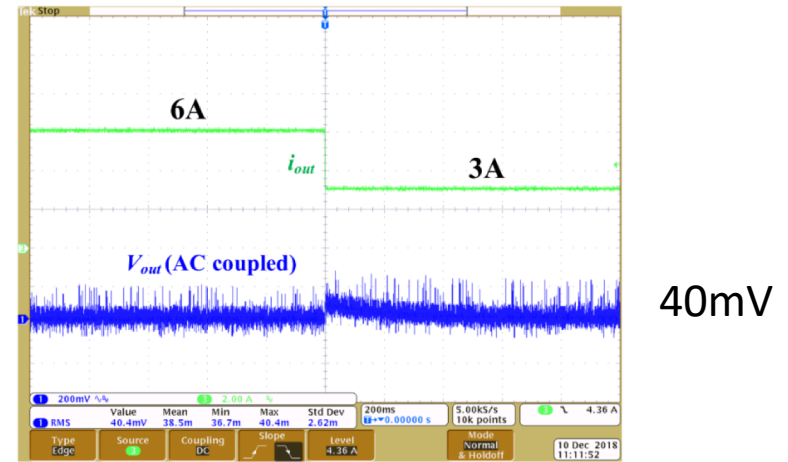
10A output current (200LFM)

The coupled inductor is still the hottest component

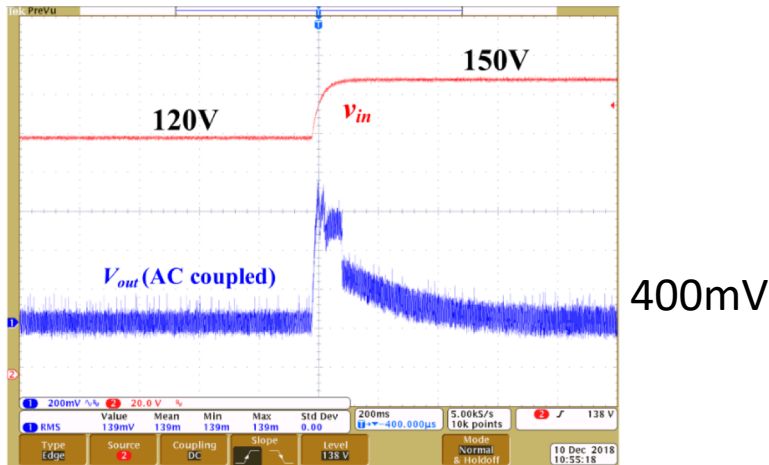
Transient response



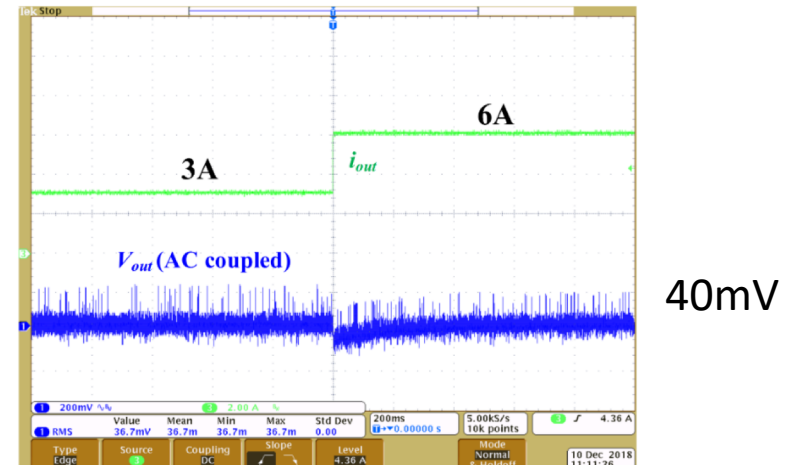
Input voltage steps down



Output current steps down



Input voltage steps up



Output current steps up

Improving dynamic response in future work

Conclusion

- **MSP architecture and LEGO building blocks**
- **Linear extendable with reduced voltage/current stresses**
- **Hybrid switched-capacitor magnetic operation**
- **Achieve high efficiency and power density across wide operation range**

Thank you!

References

1. Y. Lei, W. Liu and R. C. N. Pilawa-Podgurski, “An Analytical Method to Evaluate and Design Hybrid Switched-Capacitor and Multilevel Converters,” IEEE Transactions on Power Electronics, vol. 33, no. 3, pp. 2227-2240, March 2018.
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5. K. I. Hwu, W. Z. Jiang and Y. T. Yau, “Ultrahigh Step-Down Converter,” IEEE Transactions on Power Electronics, vol. 30, no. 6, pp. 3262-3274, June 2015.